

In re Patent Application of
LAFFOLEY
Serial No. NOT YET ASSIGNED
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In the Claims:

This listing of claims replaces all prior versions and listing of claims in the application.

Claims 1-9 (canceled).

10. (New) A method for making an electronic device comprising:

forming at least one via in a substrate;
plating the at least one via with a conductor;
cutting the substrate along a path which passes through the at least one via to form at least one contact pad, the at least one contact pad having a first portion extending across an upper surface of the substrate adjacent an edge thereof and a second portion extending from the edge across a side surface of the substrate; and

mounting an electronic component comprising at least one contact on the substrate so that the contact is electrically connected to the at least one contact pad.

11. (New) The method of Claim 10 wherein mounting further comprises:

forming a solder connection between the at least one contact and the at least one contact pad, the solder connection comprising a generally planar portion between the first portion of the at least one contact and the at least one contact pad; and

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forming a fillet portion extending angularly from the second portion of the at least one contact to the second portion of the at least one contact pad.

12. (New) The method of Claim 11 wherein forming the solder connection comprises applying solder paste between the at least one contact and the at least one contact pad and heating the assembly to cause the solder paste to flow.

13. (New) The method of Claim 12 wherein forming the solder connection further comprises orienting the electronic component in an upside down position, applying the solder paste to the electronic component, applying the support to the solder paste in the upside down position, and heating the electronic component, the support, and the solder paste.

14. (New) The method of Claim 13 wherein forming the solder connection further comprises maintaining the assembly in the upside down position during cooling.

15. (New) A method for making a printed circuit board comprising:

forming at least one via in a substrate;
plating the at least one via with a conductor;
cutting the substrate along a path which passes through the at least one via to form at least one contact pad, the at least one contact pad having a first portion extending across an upper surface of the substrate adjacent an edge thereof and a second portion extending from the edge across a side surface of the substrate.

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16. (New) A method for making an electronic device comprising:

providing a printed circuit board; and
mounting an integrated circuit on the printed circuit board, the printed circuit board having a smaller area than an area of the integrated circuit.

17. (New) The method of Claim 16 wherein the printed circuit board comprises a plurality of contact pads each having a first portion extending across an upper surface of the printed circuit board adjacent an edge thereof and a second portion extending from the edge across a side surface of the printed circuit board.

18. (New) The method of Claim 17 wherein the integrated circuit comprises a plurality of contacts corresponding to the plurality of contact pads, each of the plurality of contacts having at least a portion thereof extending across a portion of an undersurface of the integrated circuit.

19. (New) The method of Claim 18 wherein mounting the integrated circuit on the printed circuit board further comprises forming a respective solder connection between respective contacts and contact pads, each solder connection comprising a fillet portion.

20. (New) An electronic device comprising:
a printed circuit board; and

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an integrated circuit mounted on said printed circuit board, said printed circuit board having a smaller area than an area of said integrated circuit.

21. (New) The electronic device of Claim 20 wherein said printed circuit board comprises a plurality of contact pads each having a first portion extending across an upper surface of the printed circuit board adjacent an edge thereof and a second portion extending from the edge across a side surface of the printed circuit board.

22. (New) The electronic device of Claim 21 wherein said integrated circuit comprises a plurality of contacts corresponding to said plurality of contact pads, each of said plurality of contacts having at least a portion thereof extending across a portion of an undersurface of the integrated circuit.

23. (New) The electronic device of Claim 22 further comprising a respective solder connection connecting respective contacts and contact pads, each solder connection comprising a fillet portion.

24. (New) A printed circuit board for use with an integrated circuit comprising a plurality of contacts each having at least a portion thereof extending across a portion of an undersurface of the integrated circuit, the printed circuit board comprising:

a substrate; and

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a plurality of contact pads carried by said substrate and corresponding to the plurality of contacts of the integrated circuit, each contact pad having a first portion extending across an upper surface of the substrate adjacent an edge thereof and a second portion extending from the edge across a side surface of the substrate;

the substrate having a smaller area than an area of the integrated circuit.